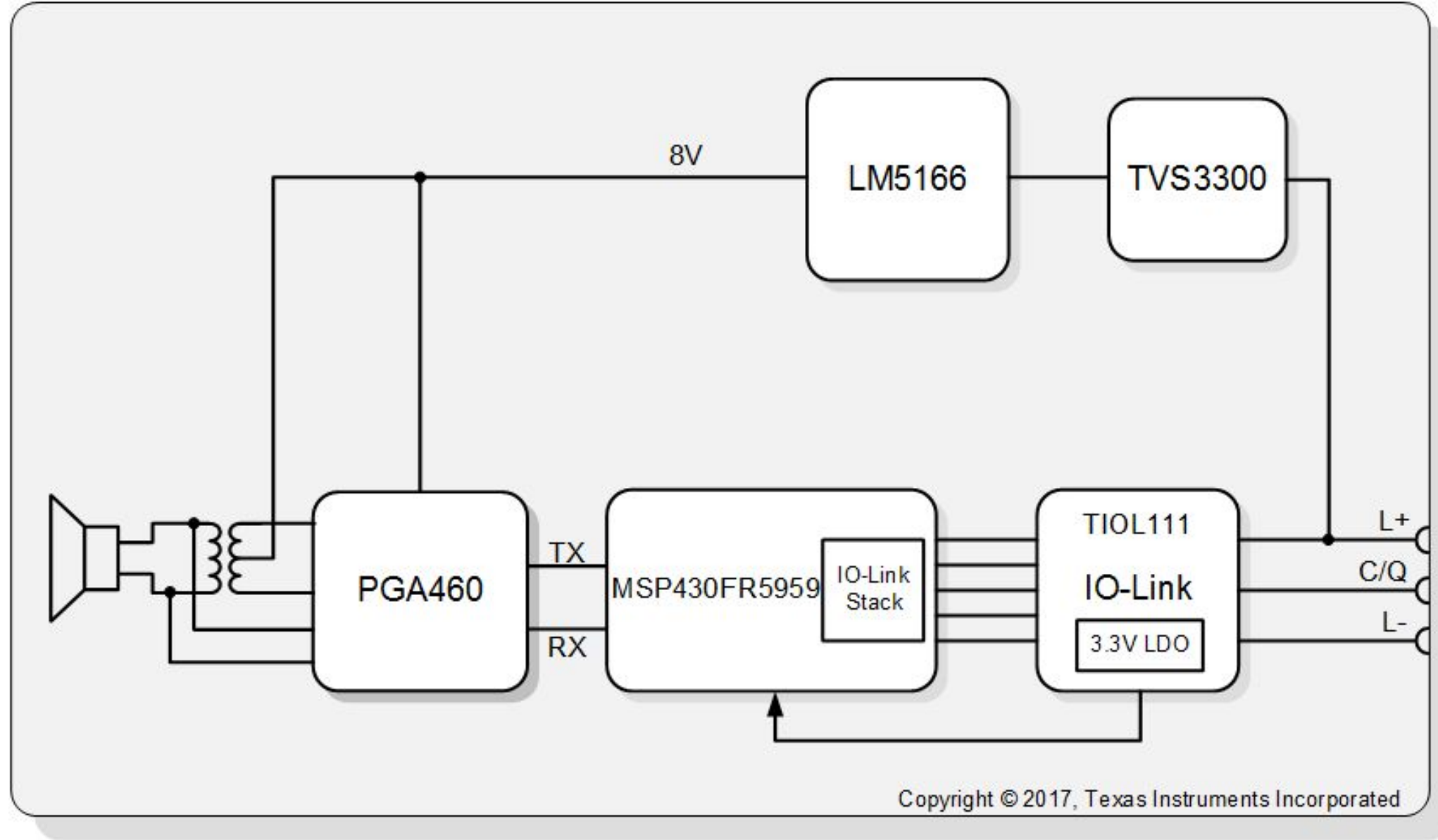


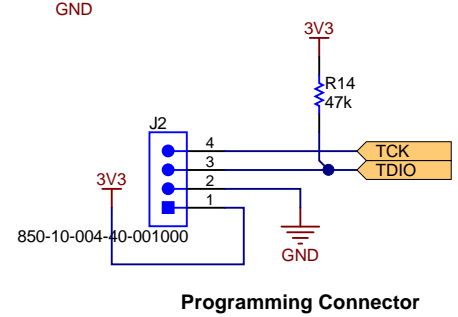
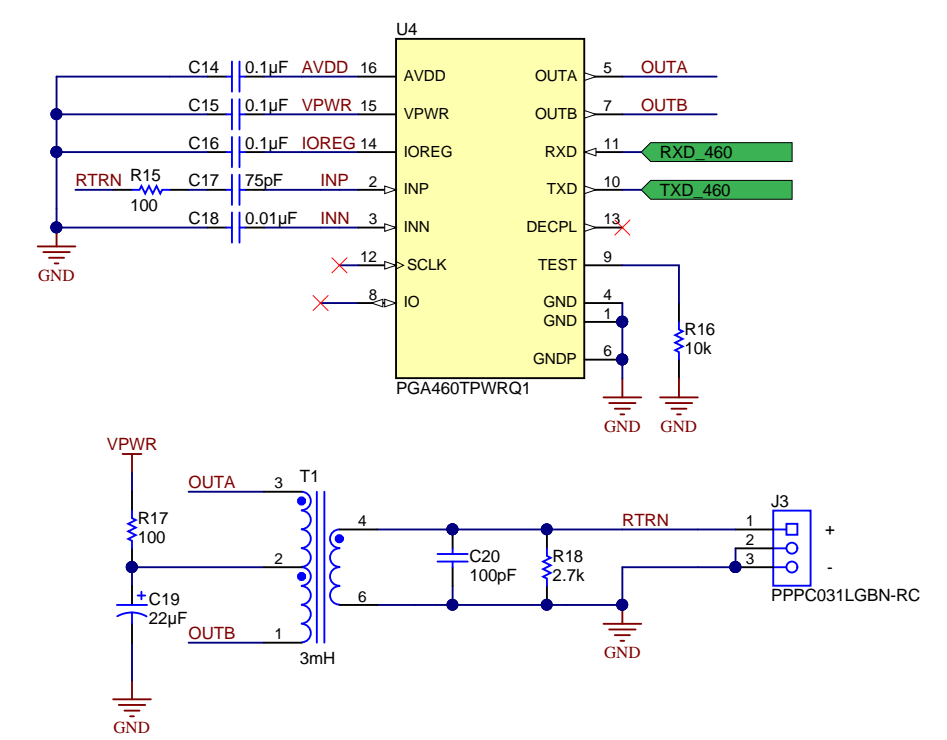
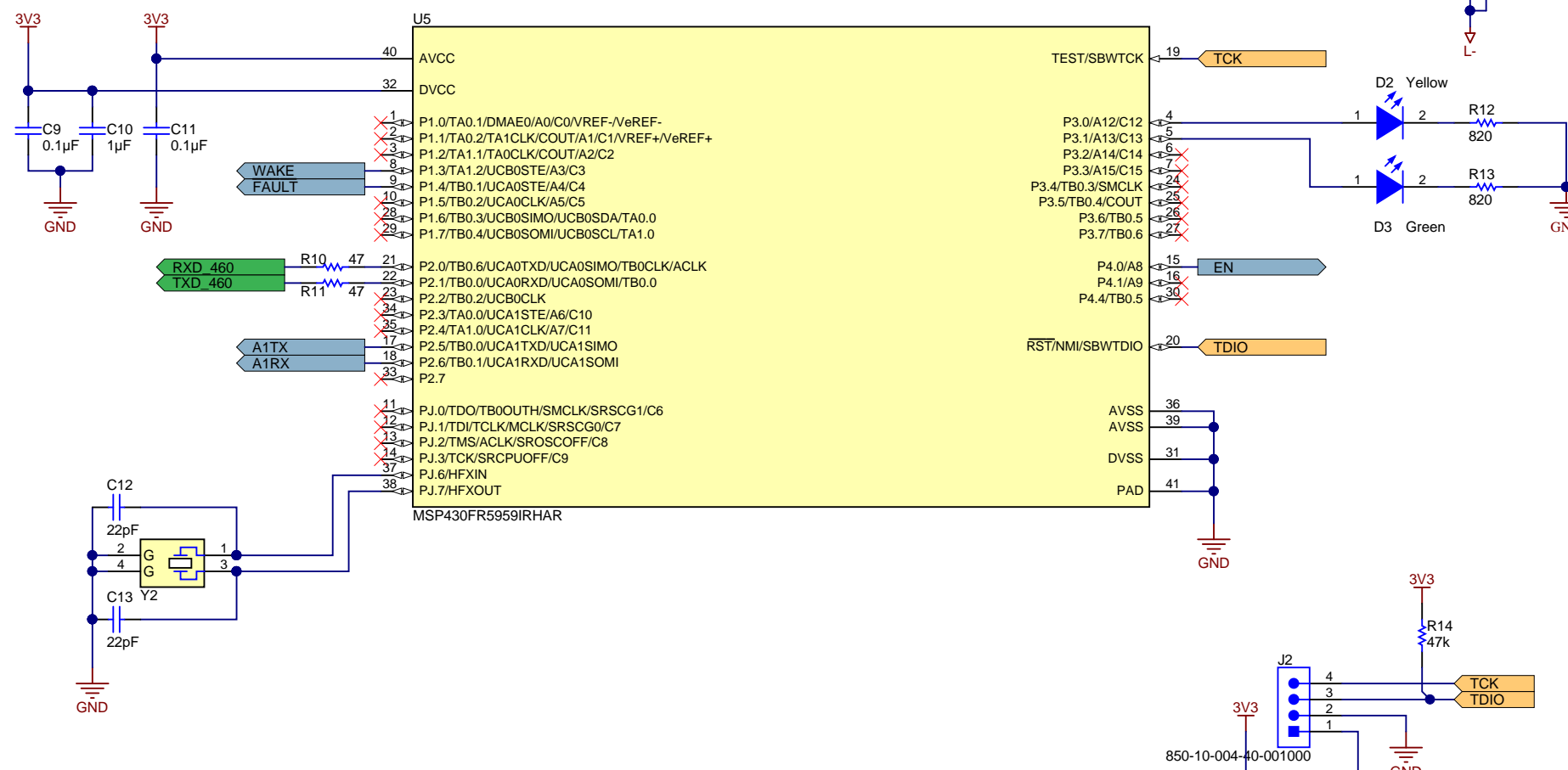
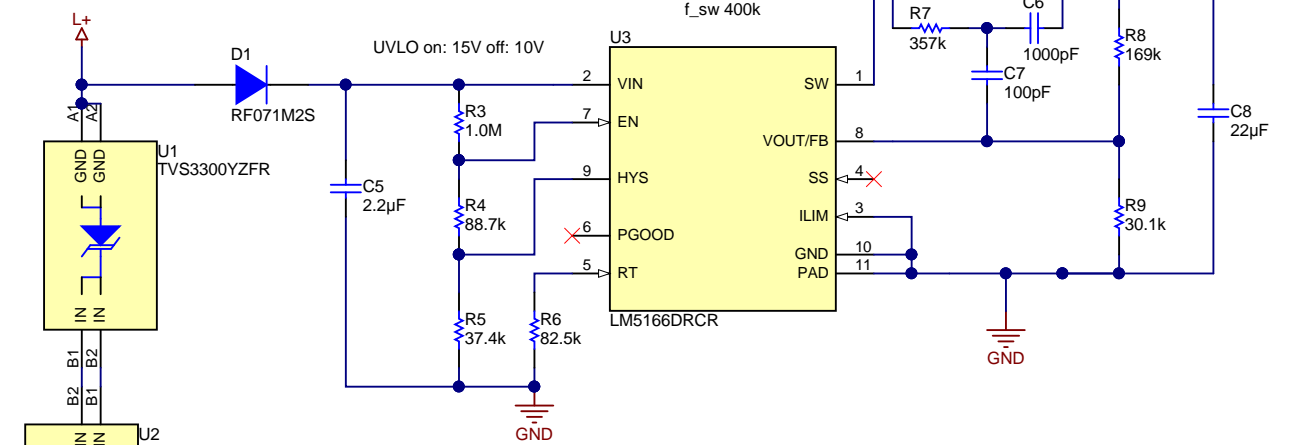
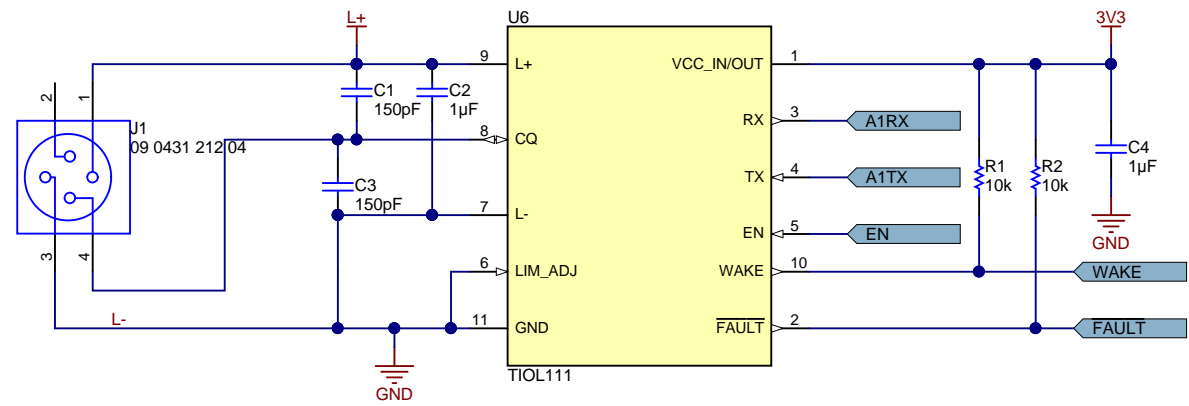
Revision History

Rev	ECN #	Approved Date	Approved by	Notes
N/A	N/A	N/A	N/A	N/A



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Orderable: N/A	Designed for: Public Release	Mod. Date: 9/11/2017	 http://www.ti.com © Texas Instruments 2017
TID #: TIDA-01386	Project Title: Ultrasonic Distance Sensor	Sheet: 1 of 3	
Number: TIDA-01386	Rev: E1	Sheet Title: Block Diagram	
SVN Rev: Version control disabled	Assembly Variant: 001	Size: B	
Drawn By: Giovanni Campanella	File: TIDA-01386E1_CoverSheet.SchDoc	Contact: http://www.ti.com/support	



Orderable: N/A	Designed for: Public Release	Mod. Date: 9/11/2017
TID #: TIDA-01386	Project Title: Ultrasonic Distance Sensor	
Number: TIDA-01386	Rev: E1	Sheet Title: Schematic
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 2 of 3
Drawn By: Giovanni Campanella	File: TIDA-01386E1_Schematic.SchDoc	Size: B
Engineer: Giovanni Campanella	Contact: http://www.ti.com/support	

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PCB Number: TIDA-01386
PCB Rev: E1

PCB LOGO
Texas Instruments

PCB LOGO
Pb-Free Symbol

PCB LOGO
FCC disclaimer

Variant/Label Table	
Variant	Label Text
001	TIDA-01386


LBL1
PCB Label
Size: 0.65" x 0.20"

ZZ1
Label Assembly Note
This Assembly Note is for PCB labels only

ZZ2
Assembly Note
These assemblies are ESD sensitive, ESD precautions shall be observed.

ZZ3
Assembly Note
These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4
Assembly Note
These assemblies must comply with workmanship standards IPC-A-610 Class 2, unless otherwise specified.

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TID #: TIDA-01386	Project Title: Ultrasonic Distance Sensor		
Number: TIDA-01386	Rev: E1	Sheet Title: Hardware	
SVN Rev: Version control disabled	Assembly Variant: 001	Sheet: 3 of 3	
Drawn By: Giovanni Campanella	File: TIDA-01386E1_Hardware.SchDoc	Size: B	
Engineer: Giovanni Campanella	Contact: http://www.ti.com/support		

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